

# MECHANICAL CASE OUTLINE

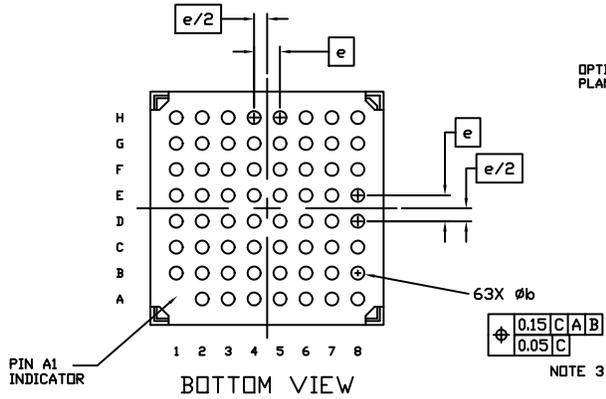
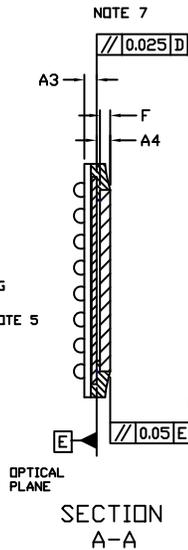
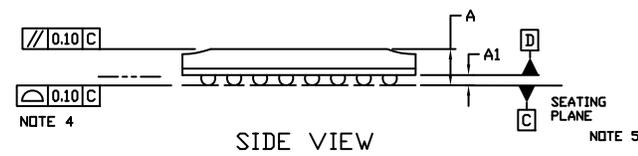
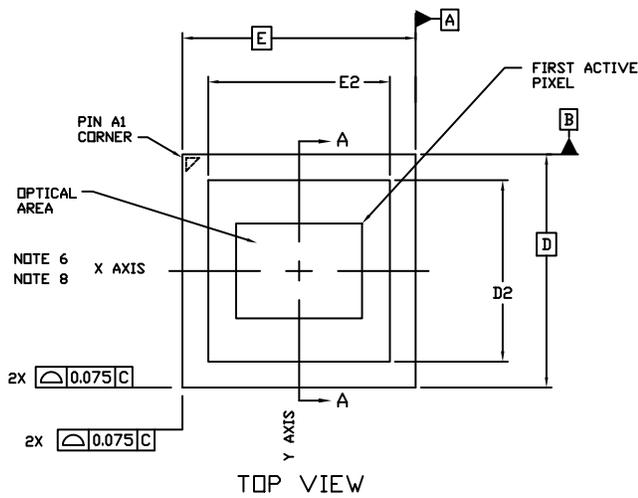
## PACKAGE DIMENSIONS

ON Semiconductor®



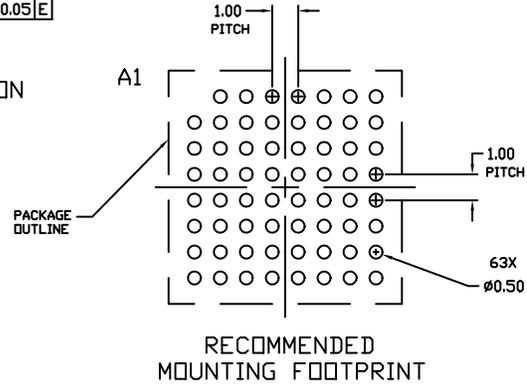
### IBGA63 9x9 CASE 503AG ISSUE A

DATE 01 FEB 2018



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS
  3. DIMENSION *b* IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
  4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
  5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
  6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO D AND E WILL BE 1°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
  7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
  8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=0.00 MICRONS, Y=0.00 MICRONS ±75 MICRONS.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.54
A1	0.34	0.44
A3	0.425	0.525
A4	0.475	0.575
<i>b</i>	0.45	0.55
D	9.00 BSC	
D2	6.90	7.10
E	9.00 BSC	
E2	6.90	7.10
<i>e</i>	1.00 BSC	
F	0.35	0.45



DOCUMENT NUMBER:	98AON93394F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
REFERENCE:		
DESCRIPTION:	IBGA63 9X9	PAGE 1 OF 2

